

Overview of the ATLAS High-Granularity Timing Detector: project status and results

YE, Jingbo on behalf of the ATLAS HGTD Group
Institute of High Energy Physics, Chinese Academy of Sciences

At HSTD13, Dec. 5, 2023



中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

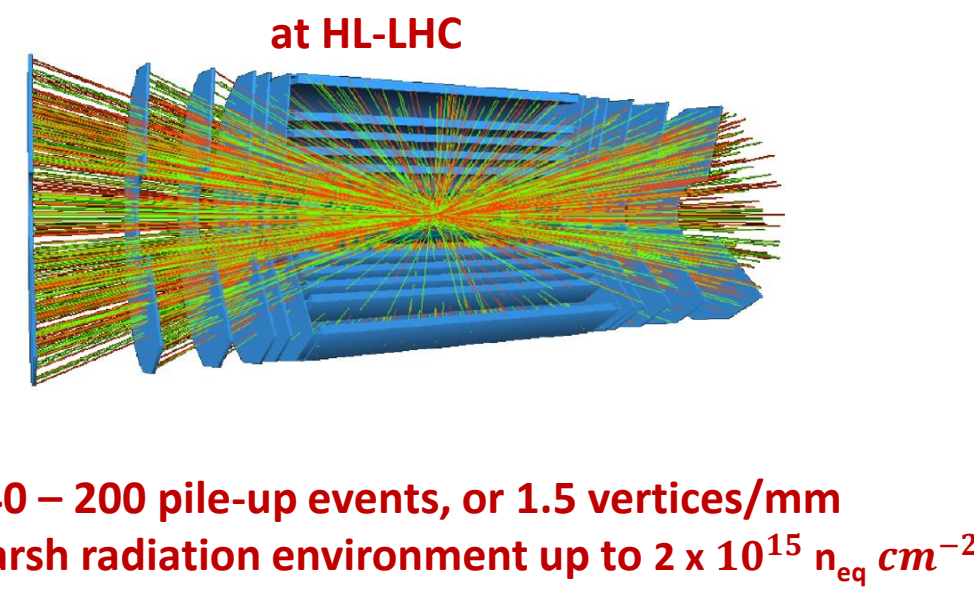
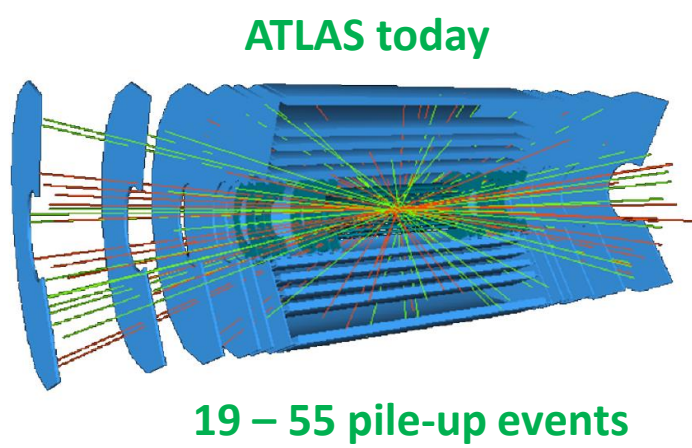
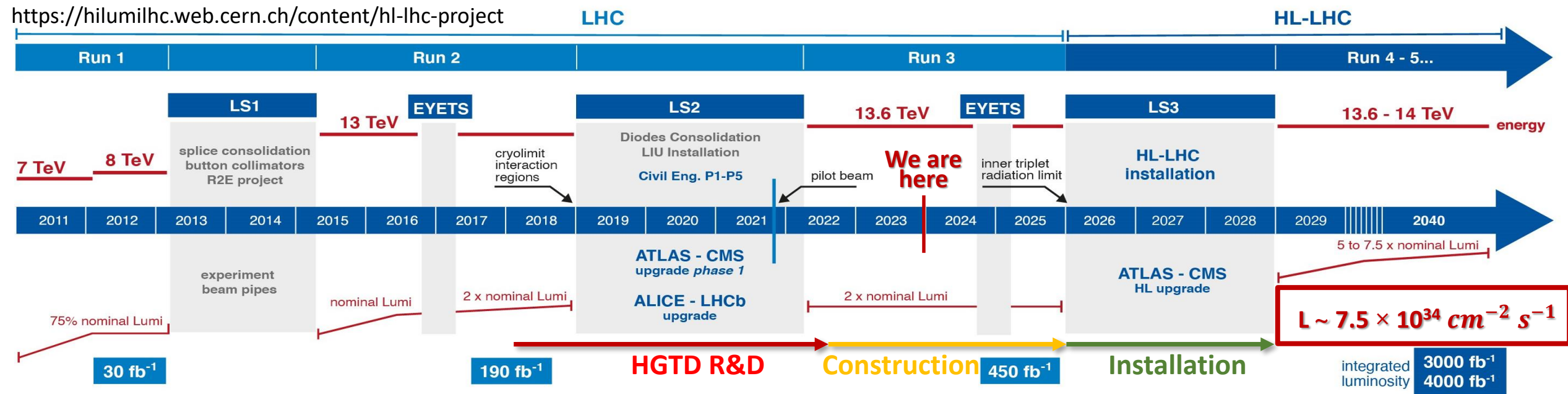
**13th International “Hiroshima”
Symposium on the Development and
Application of Semiconductor
Tracking Detectors (HSTD13)**





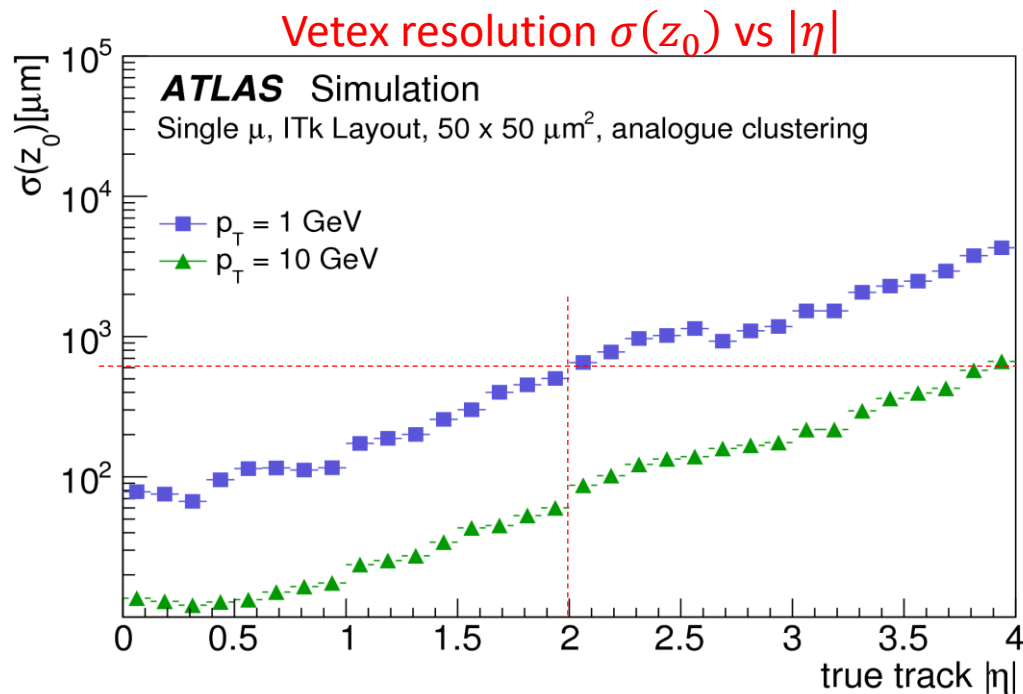
- The motivation
- The HGTD in a nutshell
- Some highlights: the LGAD sensors, the readout ASIC ALTIROC, and some beam test results; the module assembly and the peripheral electronics board (PEB)
- The status and a summary

<https://hilumilhc.web.cern.ch/content/hl-lhc-project>



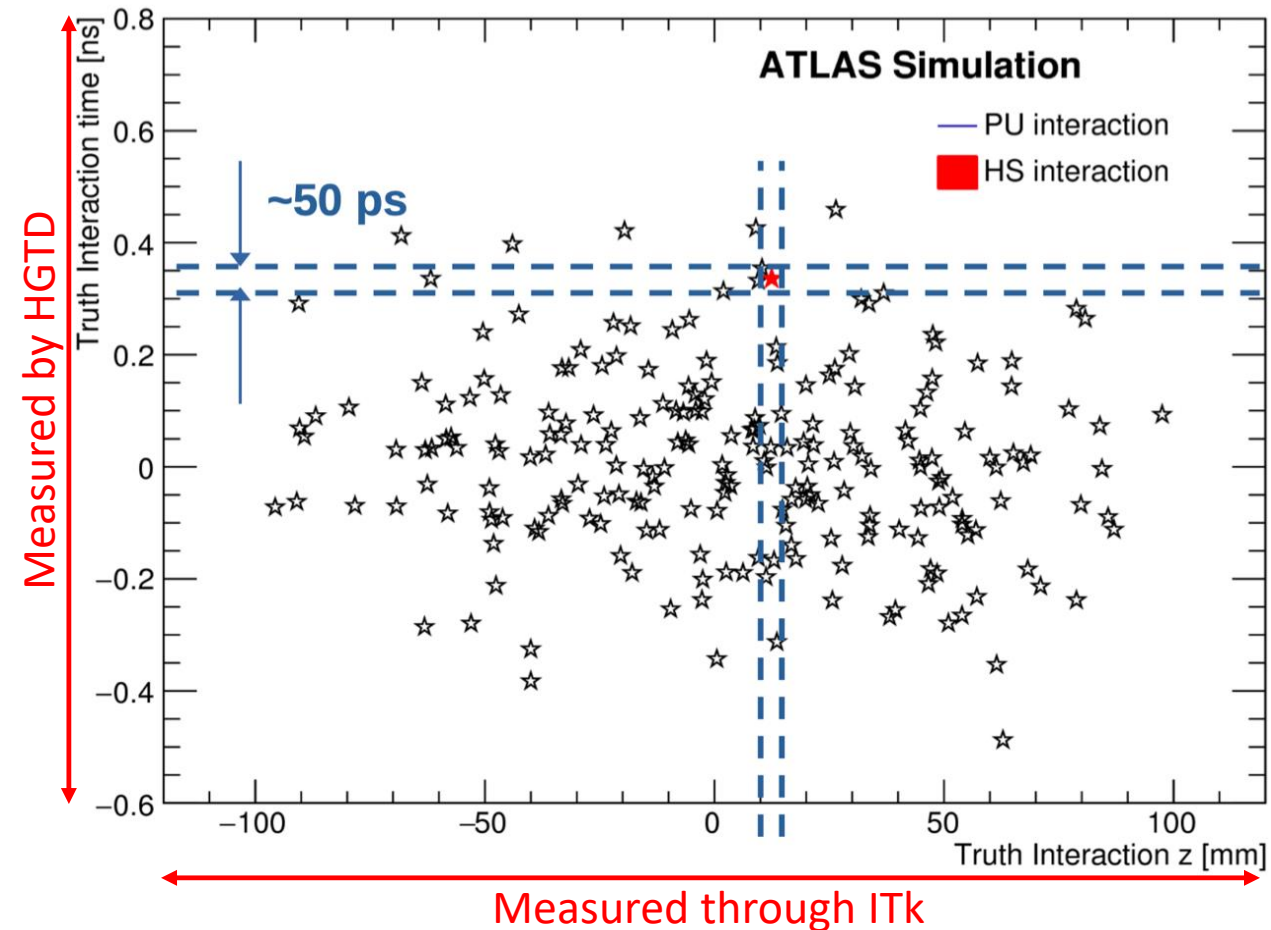
The challenges:

- At the interaction point, about 45 mm along the beam axis, we expect ~ 200 pile-ups, or **1.5 vertices/mm**
- Although the ATLAS Inner Tracker (ITk) is designed to cope with this pile-up density, it is challenging when $|\eta| > 2$: σ_{z_0} needs to be $< 0.6\text{mm}$ to distinguish individual vertex.



The solution:

- Separate the vertices (pile-ups) also in time
- With 50 ps MIP time resolution, the pile-up suppression is expected to improve by a **factor of ~ 6**

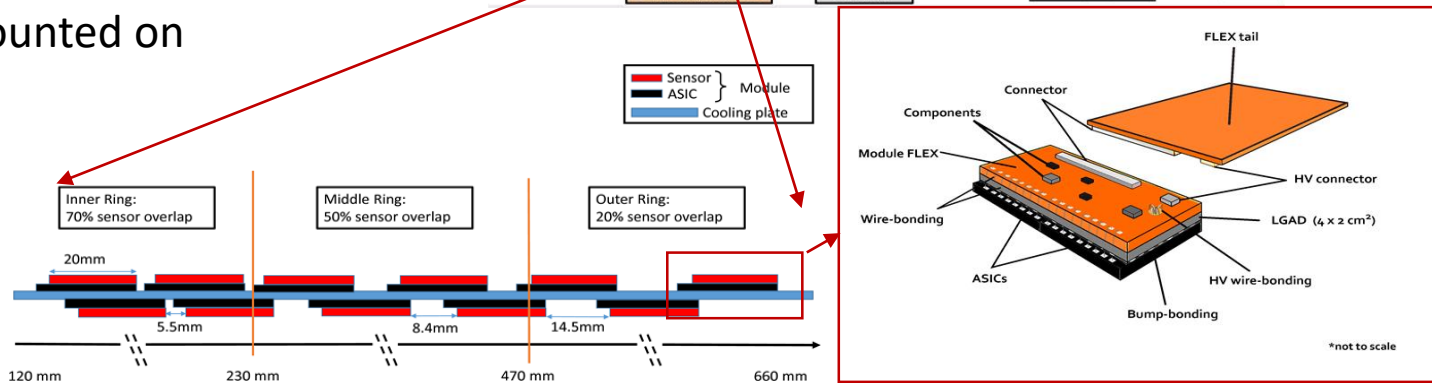
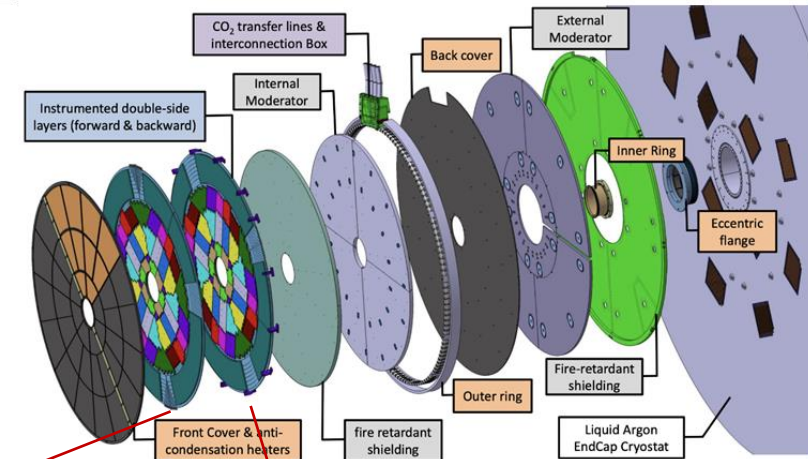
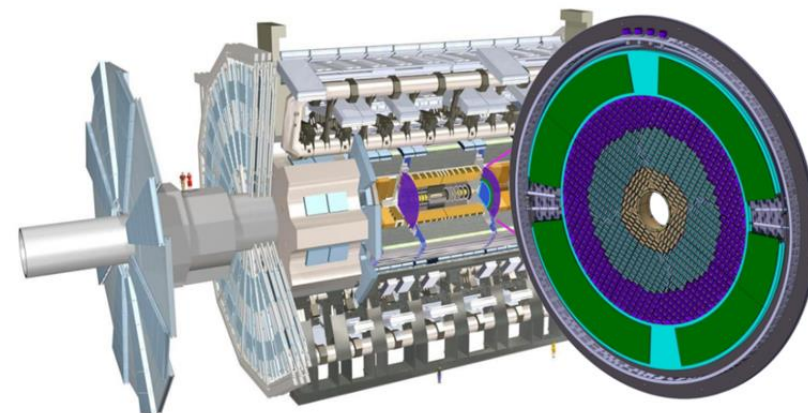


The HGTD is designed to provide timing information for ATLAS at the HL-LHC

- 6.4 m² silicon detector and about 3.6×10^6 channels
- Based on the Low Gain Avalanche Detector (LGAD) sensor, 1.3 mm × 1.3 mm, able to work in the ATLAS detector environment
- Design time resolution: 30 – 50 ps/track (start to end-of-life),
- Provide luminosity measurement
 - Count number of hits at 40 MHz (bunch-by-bunch)
 - Goal for HL-LHC: 1% luminosity Uncertainty

The two detectors are located between the barrel and the endcap calorimeters

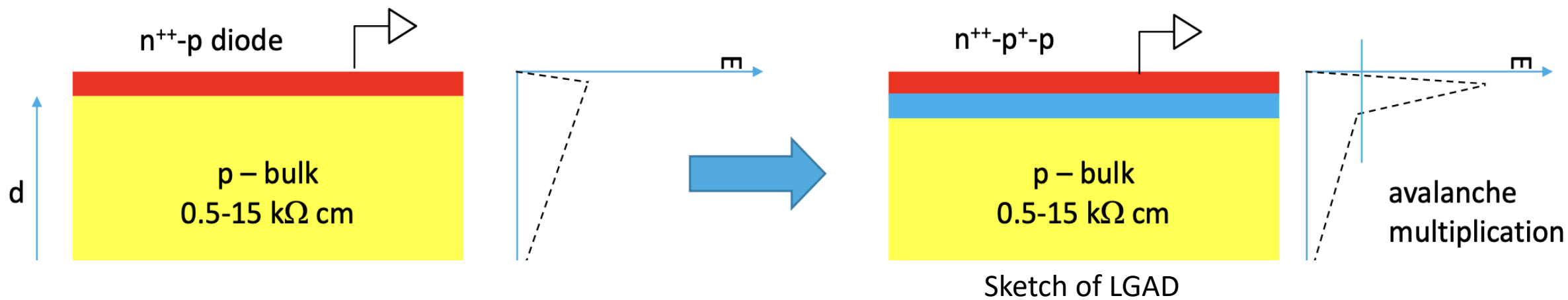
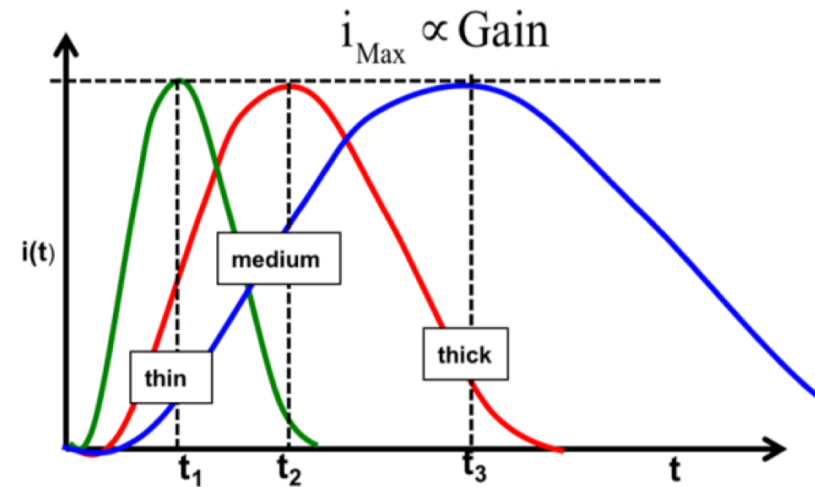
- Each detector (end) has two disks with sensors mounted on both sides
- Located at ± 3.5 m from the interaction point
- Active area coverage: $2.4 < |\eta| < 4$
- Radius: $120 \text{ mm} < r < 640 \text{ mm}$



Compared with APD and SiPM, LGAD has

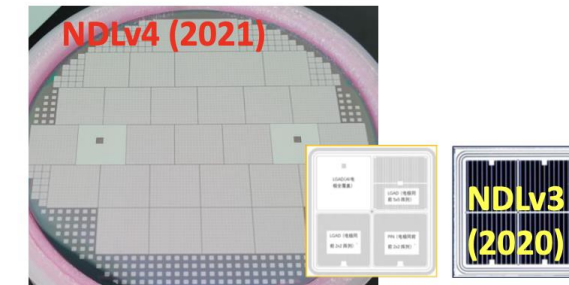
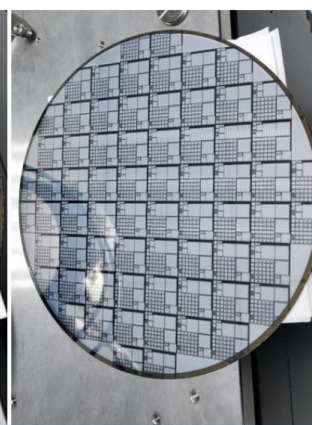
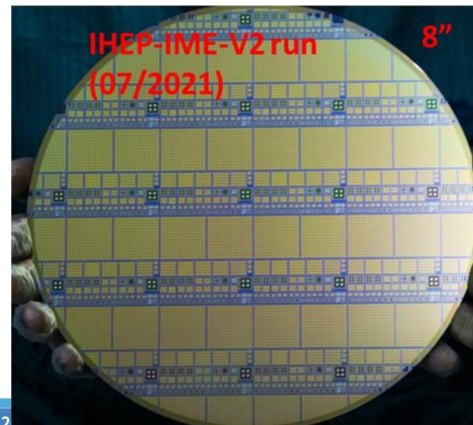
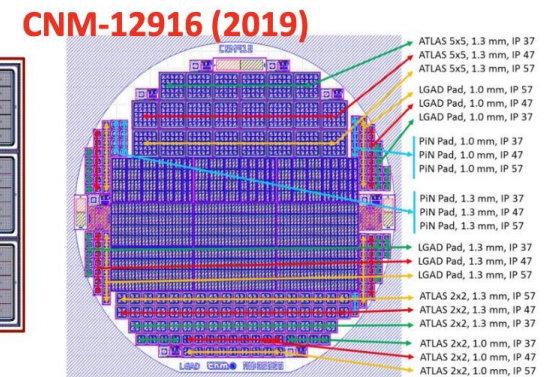
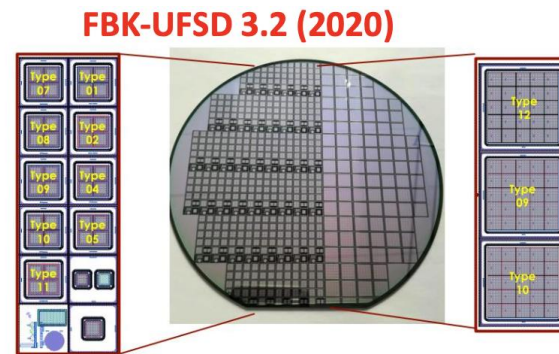
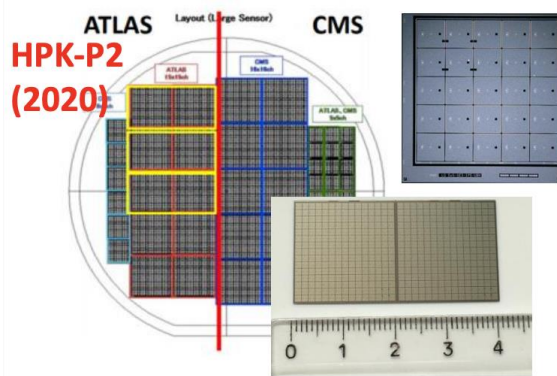
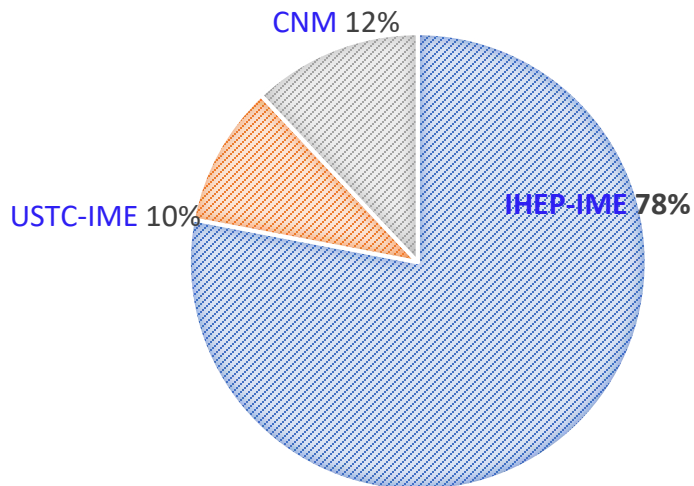
- modest gain (10-50) to increase the S/N
- High drift velocity, thin active layer to decrease the t_{rise} (fast timing), leads better time measurement:

$$\sigma_{jitter}^2 = \left(\frac{t_{rise}}{S/N} \right)^2$$



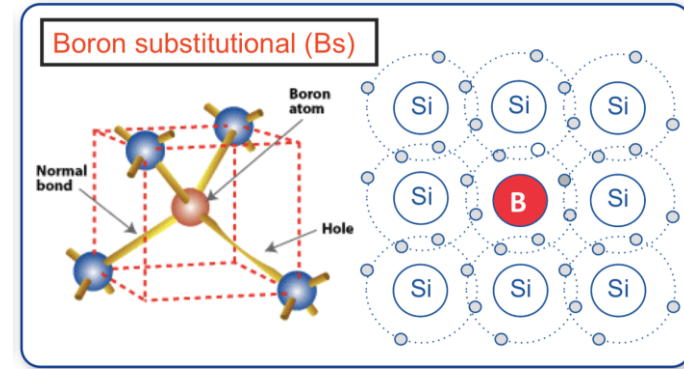
- The last few years saw increased efforts in LGAD R&D. The active entities include: IHEP-IME (China), USTC-IME (China), IHEP-NDL(China), FBK (Italy), CNM (Spain), HPK (Japan) ...
- HGTD has finalized the CERN tendering. The preliminary production plan:
 - IHEP-IME: **78%** (54% from CERN tendering+24% in-kind contribution)
 - CNM: **12%** in-kind contribution
 - USTC-IME: **10%** in-kind contribution

Share of production between providers

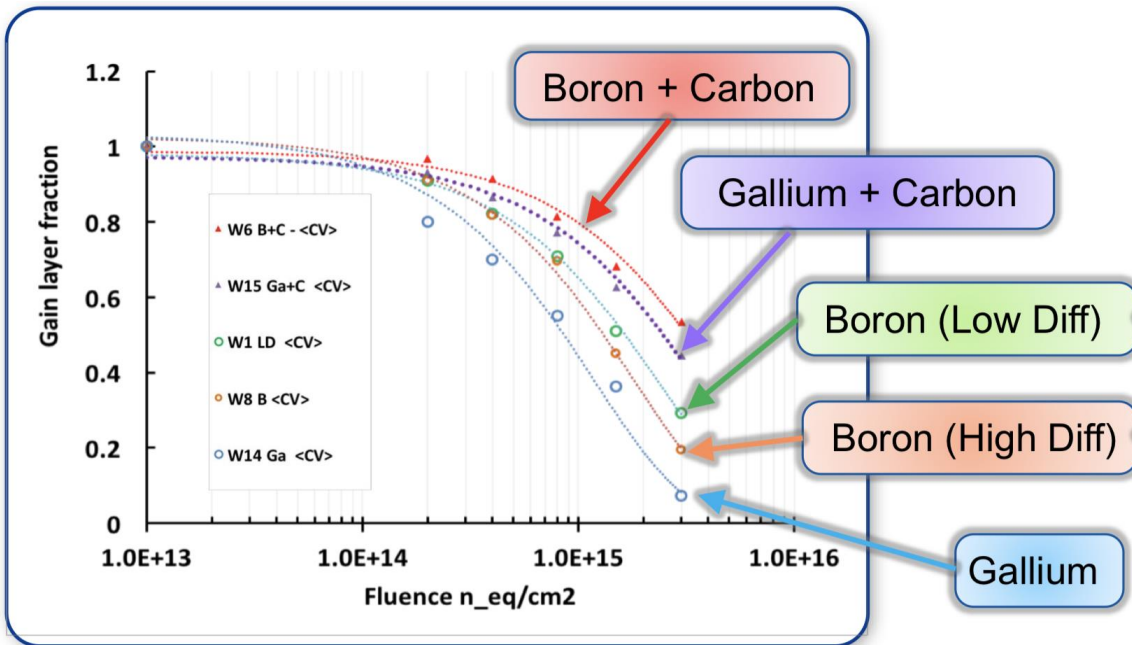


PLANAR TECHNOLOGY – more vendors (e2V, BNL, Micron ...)

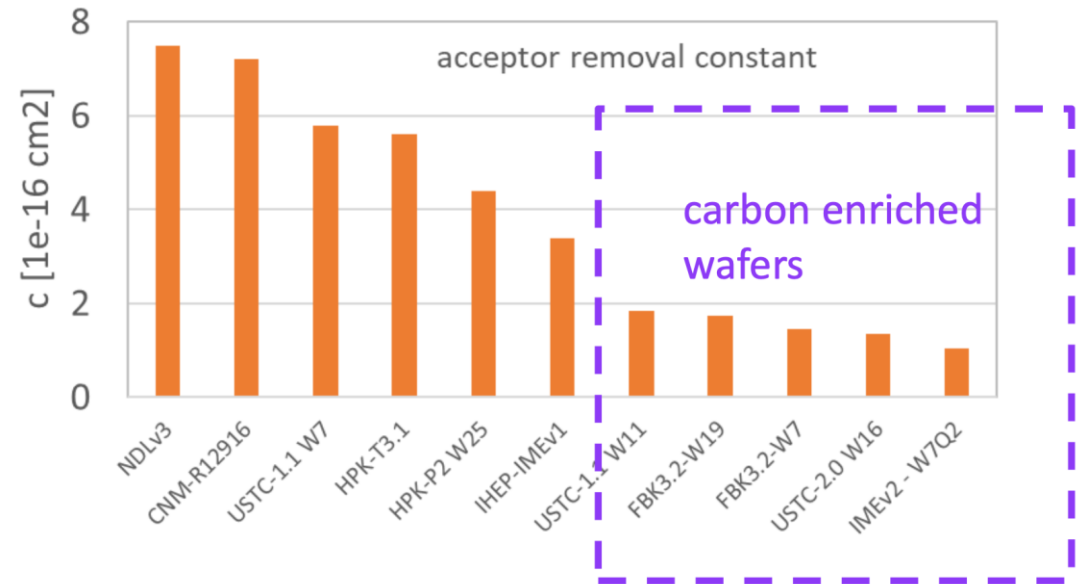
- Radiation causes boron doping in gain layer less active (acceptor removal). This can be mitigated by carbon-enriched LGAD, in which the carbon “stabilizes” the boron doping,
- The IHEP-IME/FBK/USTC-IME LGAD with carbon
 - Lower the acceptor removal ratio
 - Making the sensor more radiation tolerant



See CERN Detector seminar
<https://indico.cern.ch/event/1088953/>

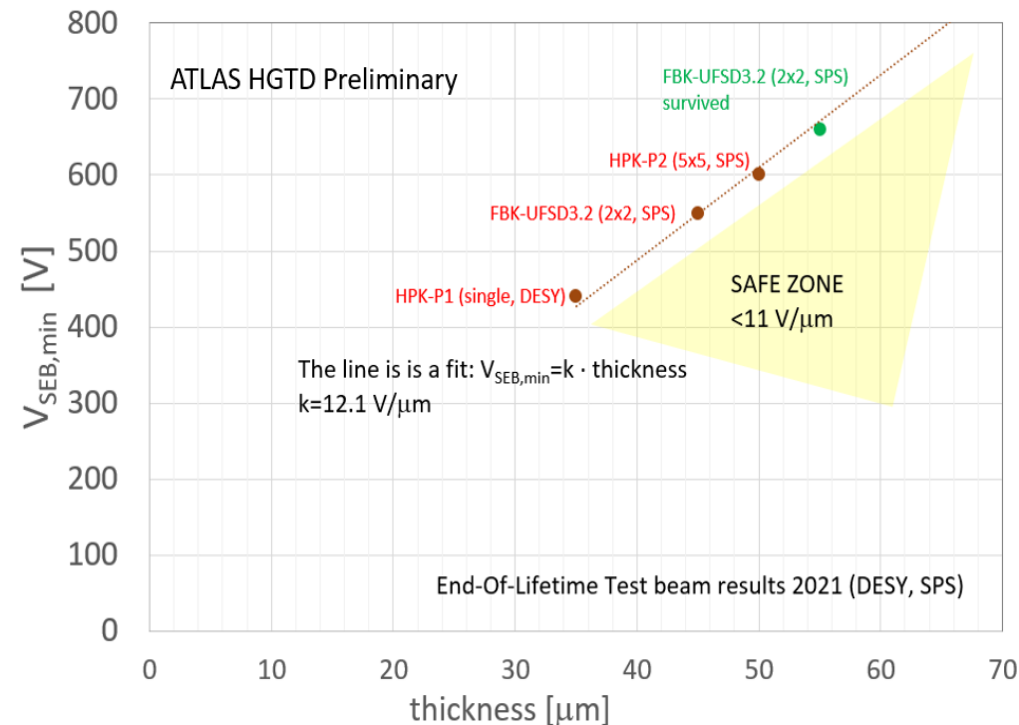


[G.Patermoster, FBK, Trento, Feb.2019]

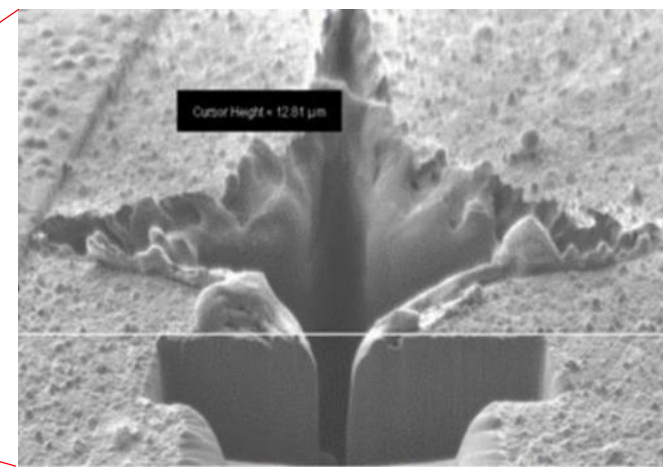
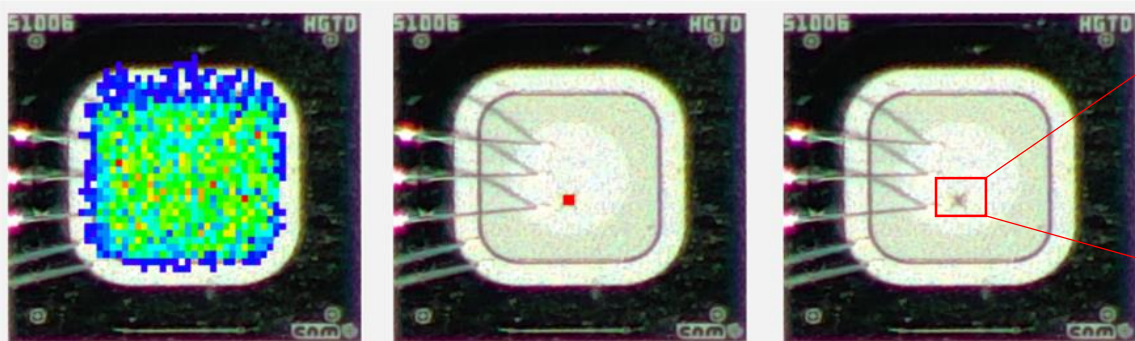


Single Event Burnout (SEB)

- Single Event Burnout (SEB) has been observed in several beam-tests
 - Radiation degrades timing performance due to the loss of gain
 - Increase the bias voltage (HV) to mitigate, but too high HV causes breakdown in the sensor
 - Also observed by CMS/ATLAS/RD50 teams
- A safe zone has been defined
 - Safe zone $< 11 \text{ V}/\mu\text{m}$, in our case (LGAD $50 \mu\text{m}$) the maximum voltage is 550 V



ATLAS HGTD Preliminary

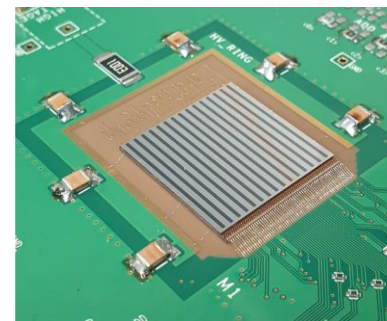
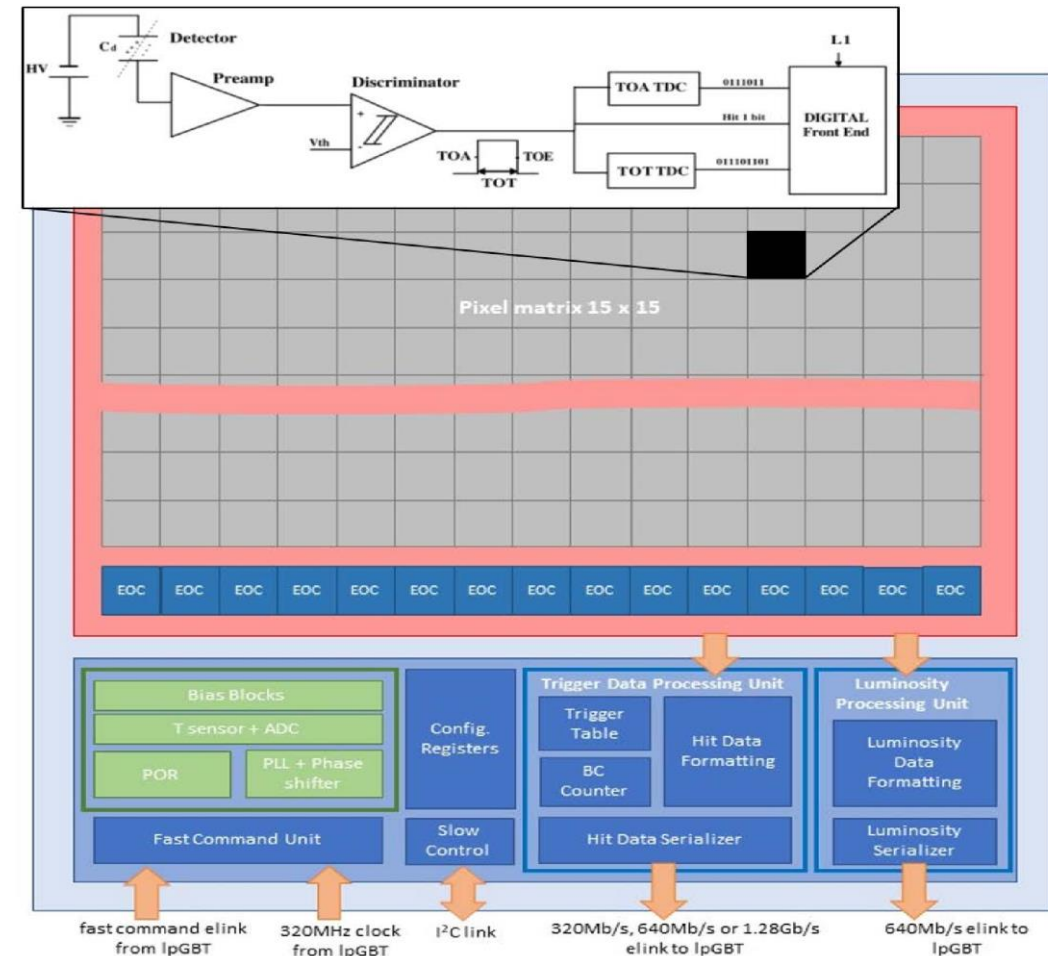


- **ALTIROC (based on a CMOS 130 nm technology)**

- Has 225(15x15) channels, matching the sensor number and pad size (1.3mm x 1.3 mm)
- Measure the Time Of Arrival (TOA), Time Over Threshold (TOT, for time walk correction) of each sensor
- Minimum discriminator threshold: 2 fC
- Timing resolution: **Jitter < 25 ps @ 10 fC and <65 ps @ 4 fC**

- **ALTIROC prototypes**

- **ALTIROC1:** 25 (5x5) channels, with all analog functionalities, tested
- **ALTIROC2:** a full-scale prototype of 225 (15x15) channels, including all functionalities, tested
- **ALTIROC3:** the radiation-tolerant version of ALTIROC2 (under test)

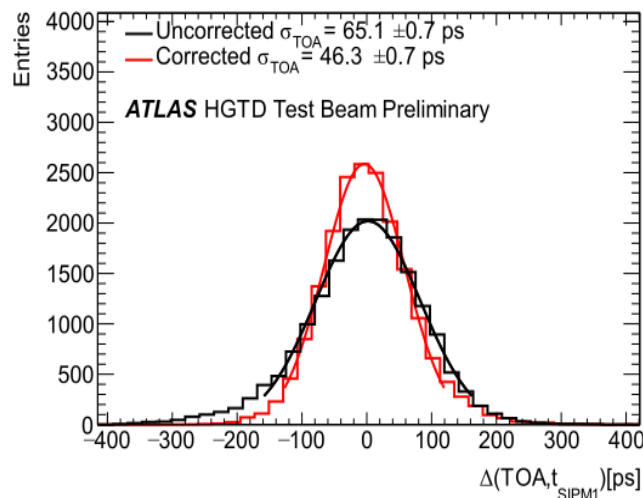


ALTIROC2 + HPK 15x15 LGAD

Beamtest results:

• ALTIROC1

- Confirm the performance of analogue circuits
- A fit of TOA as a function of TOT is used to calculate for the corrections of time-walk
- After the correction, the estimated resolution is about 46 ps
- The estimated jitter contribution is about 39 ps.

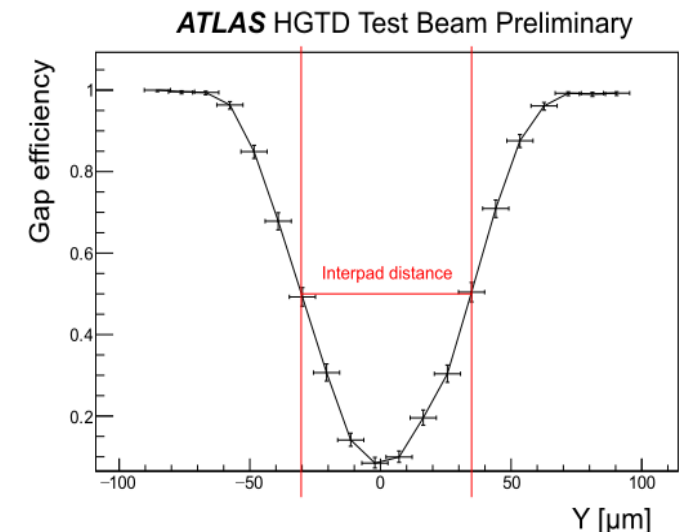
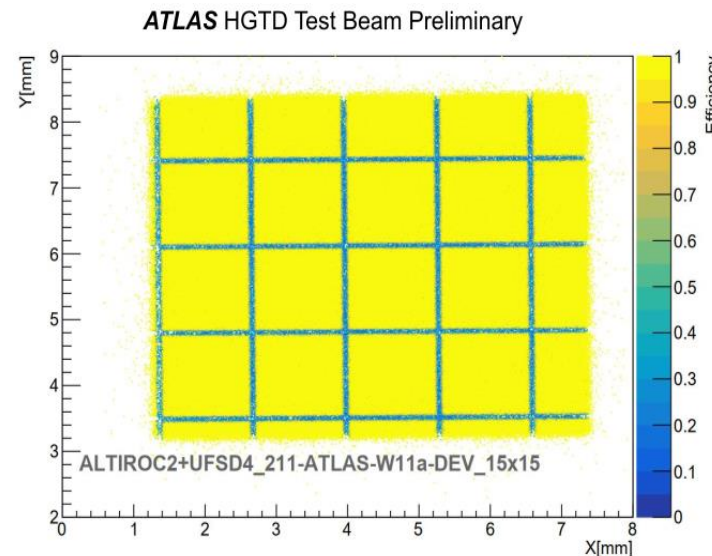


• ALTIROC2

- 100% efficiency for each pixel outside gaps

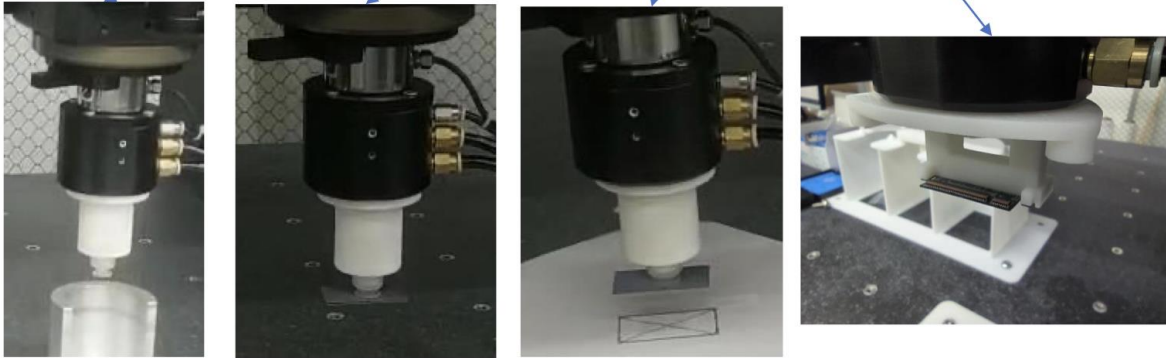
$$\text{Hit Efficiency} = \frac{\text{the reconstructed tracks with a hit seen by ALTIROC}}{\text{all reconstructed tracks that hit module area}}$$

- A gap in the inter sensor pad region is 65.3 +/- 0.2 μm defined at efficiency below 50%



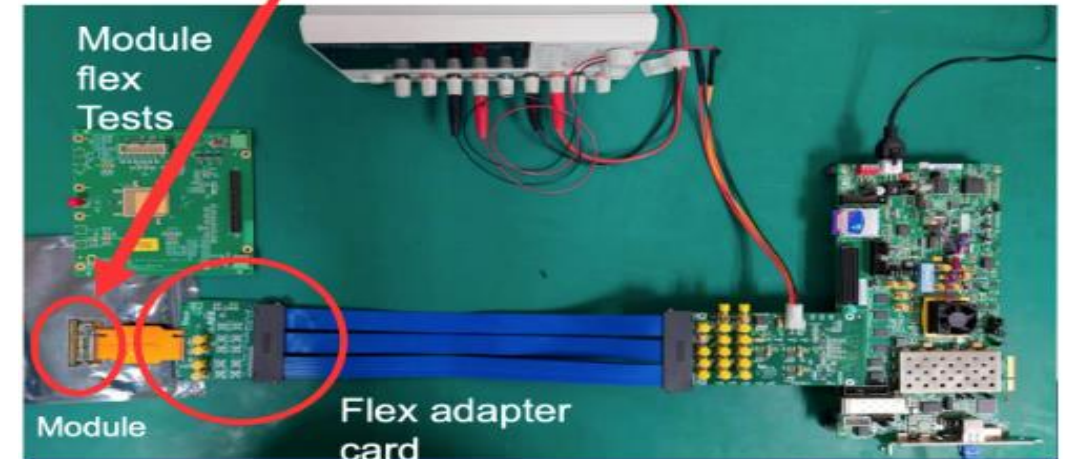
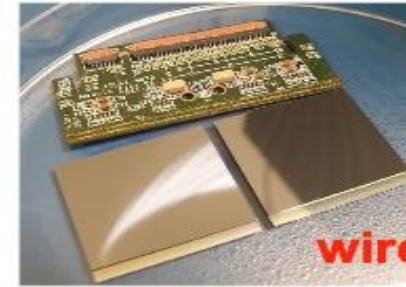
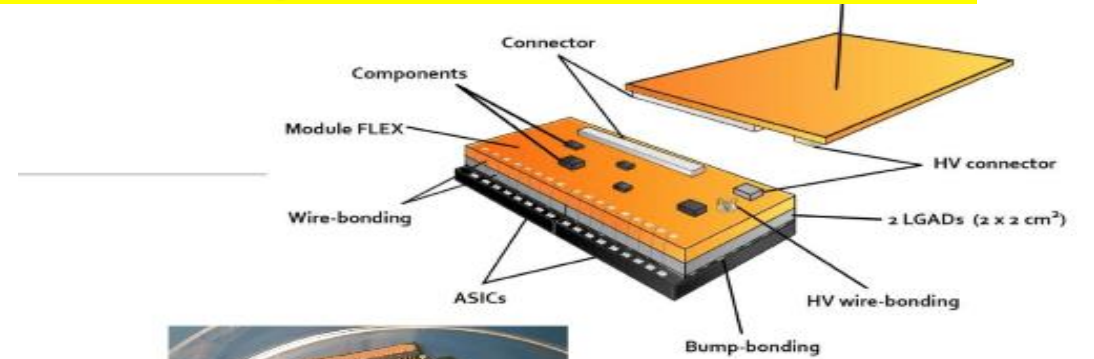
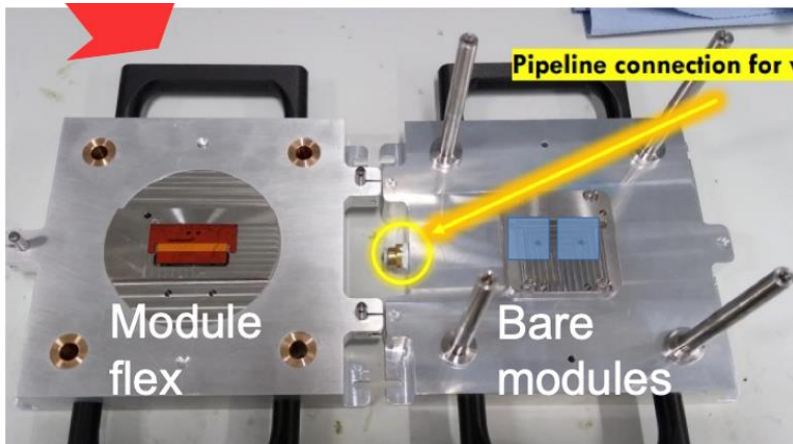
Jigs and pick-and-place machine are being developed

pick-and-place machine



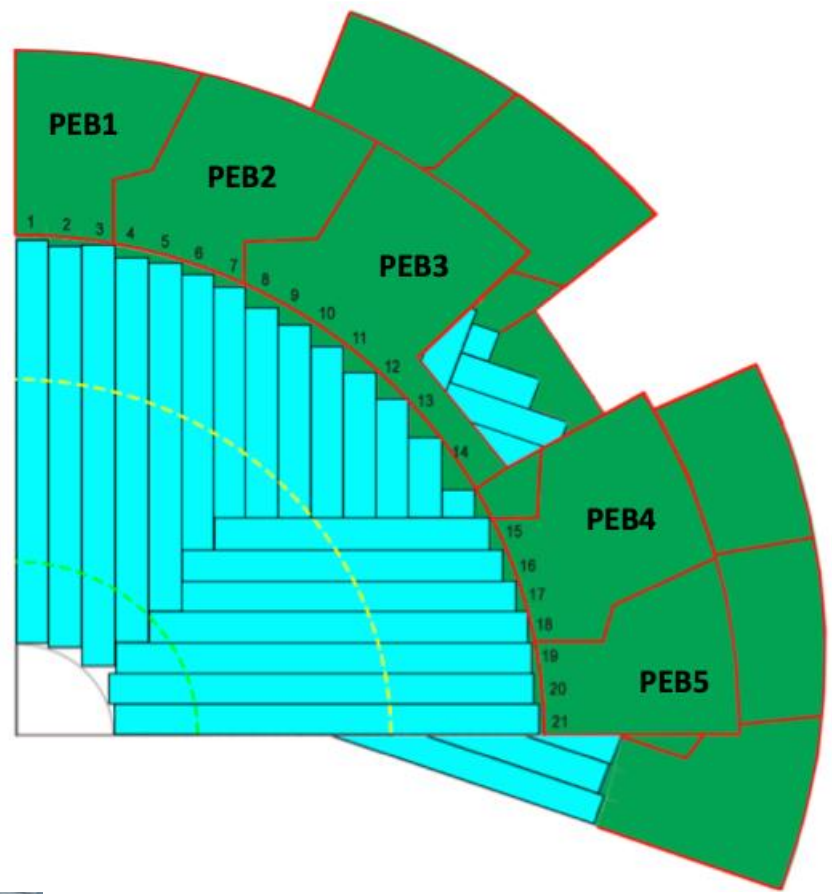
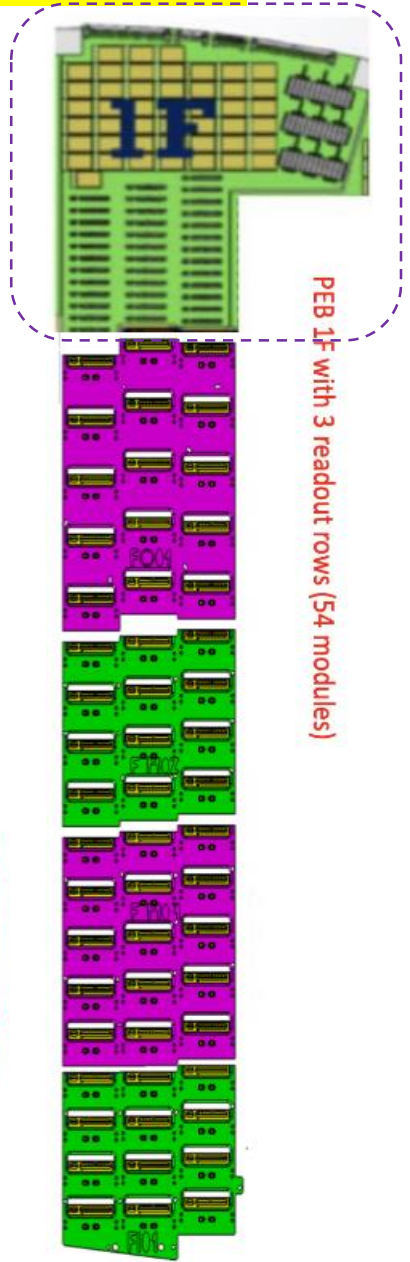
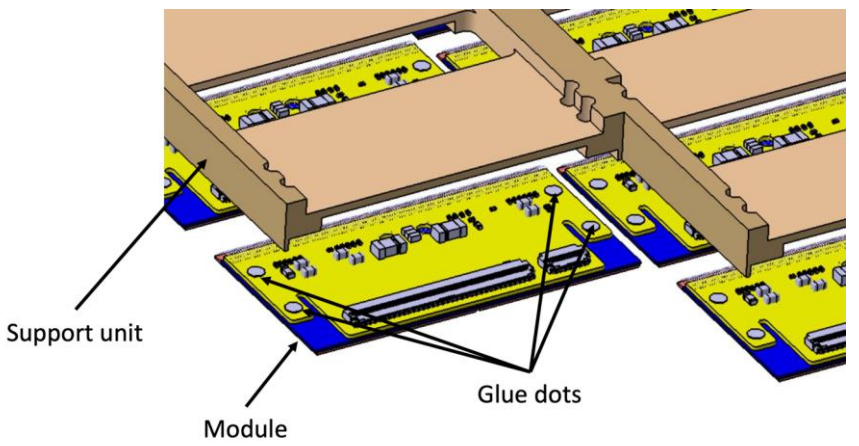
Picking tool Picking dummy sensor Placing dummy sensor Picking flex

Jigs for module assembly

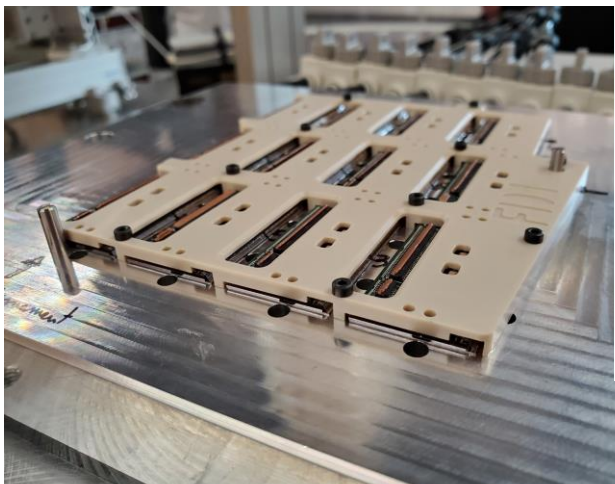


Modules are installed and glued on support units (PEEK), Challenges : machining of PEEK (flatness $<200\mu\text{m}$)

The peripheral electronics board



Glue and load the modules on the support units



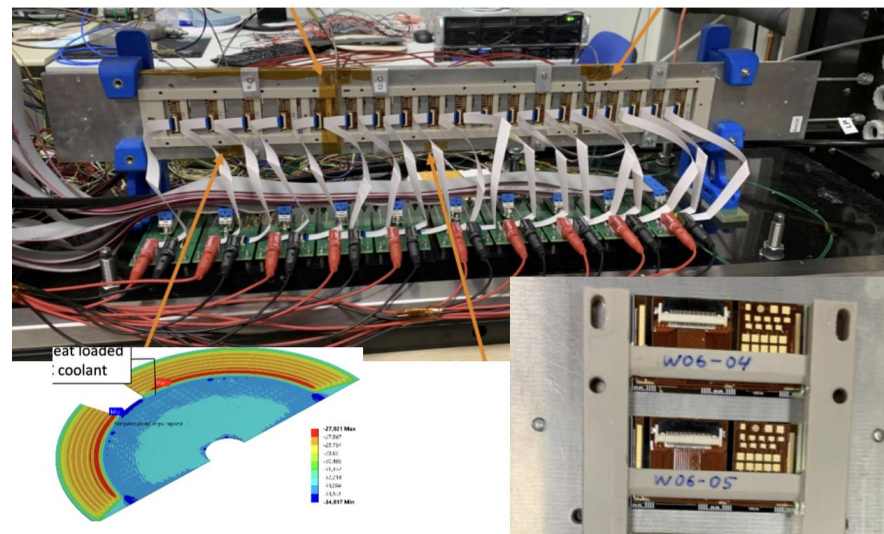
The heater demonstrator

- 19 silicon heaters mounted on a single stave
- Representing modules dissipating heat
- on the cooling plate (CO₂ cooling)

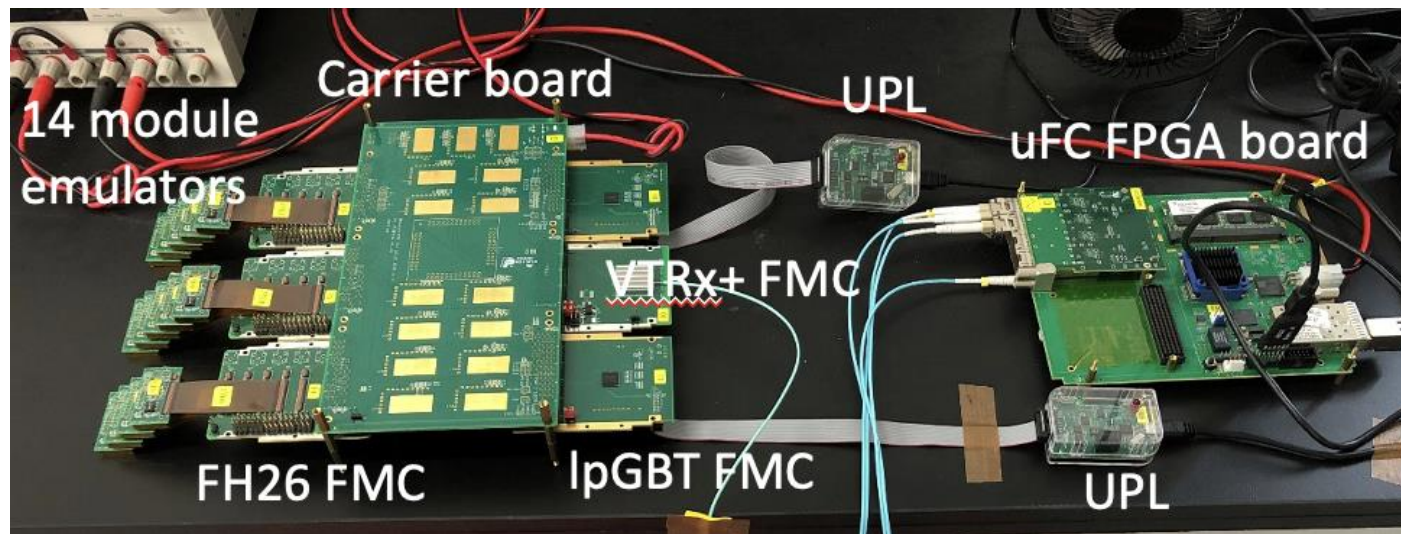
The DAQ demonstrator

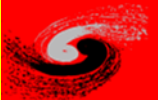
- A minimum system for the full chain readout, from the module emulator boards to the FELIX board
- Support up to 14 modules with two IpGBTs and one VTRx+
- Timing
 - Up to 3 modules @ 1.28 Gbps
 - Up to 7 modules @ 640 Mbps
 - Up to 14 modules @ 320 Mbps
- Luminosity
 - 7 modules @ 640 Mbps

The heater demonstrator



The DAQ demonstrator





- **Good progress in LGAD, meeting the requirements of HGTD**
 - Carbon enriched LGADs meet radiation tolerance requirements
 - Sensor pre-production has started
- **Two rounds of the full-size readout ASICs ALTIROC have been prototyped, so far all circuit blocks are functional, modules with ALTIROC3 are under test**
- **Module assembly is making progress**
- **The Peripheral Electronics Boards are being developed and tested**
- **Two demonstrators are used to check heat removal and the full readout chain**
- **The next milestones:**
 - 2023: Start the PEB and LGAD sensor production, (met)
 - 2024: Start the ALTIROC ASIC, Module and the detector unit production,
 - 2026-2027: the HGTD detector Integration at CERN, and the installation.

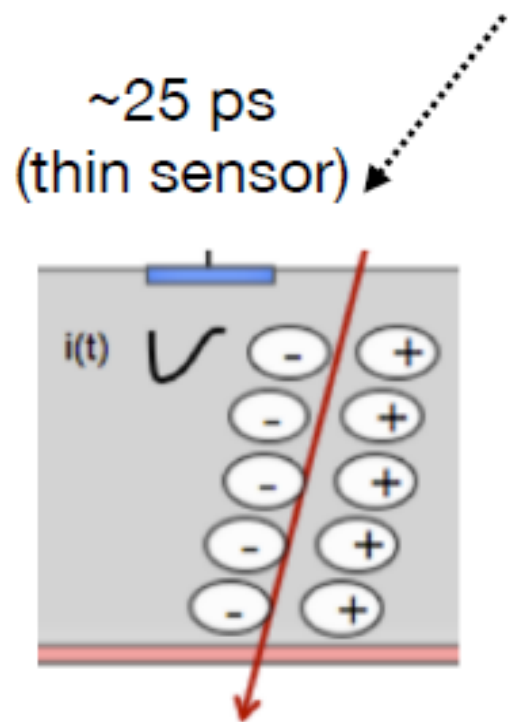


Thank You!
And Questions?

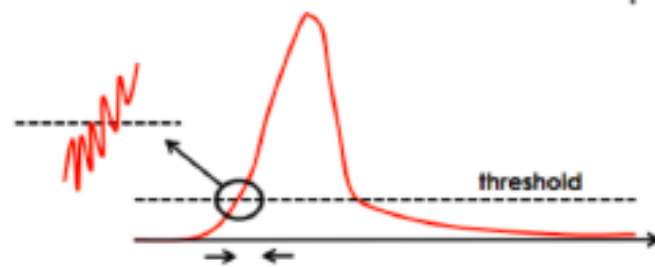
Backup Slides

overview of contributions to the time resolution:

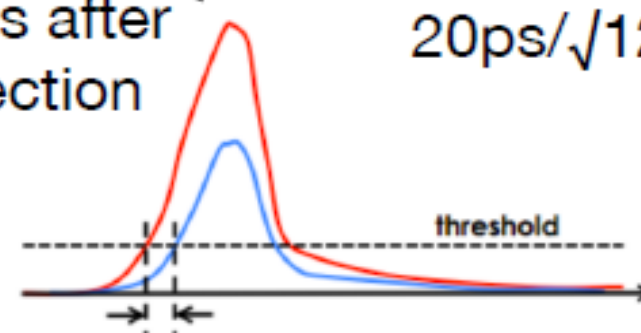
$$\sigma_{hit}^2 = \sigma_{Landau}^2 + \sigma_{jitter}^2 + \sigma_{time-walk}^2 + \sigma_{TDC}^2 + \sigma_{clock}^2$$



<25 ps at
large gain

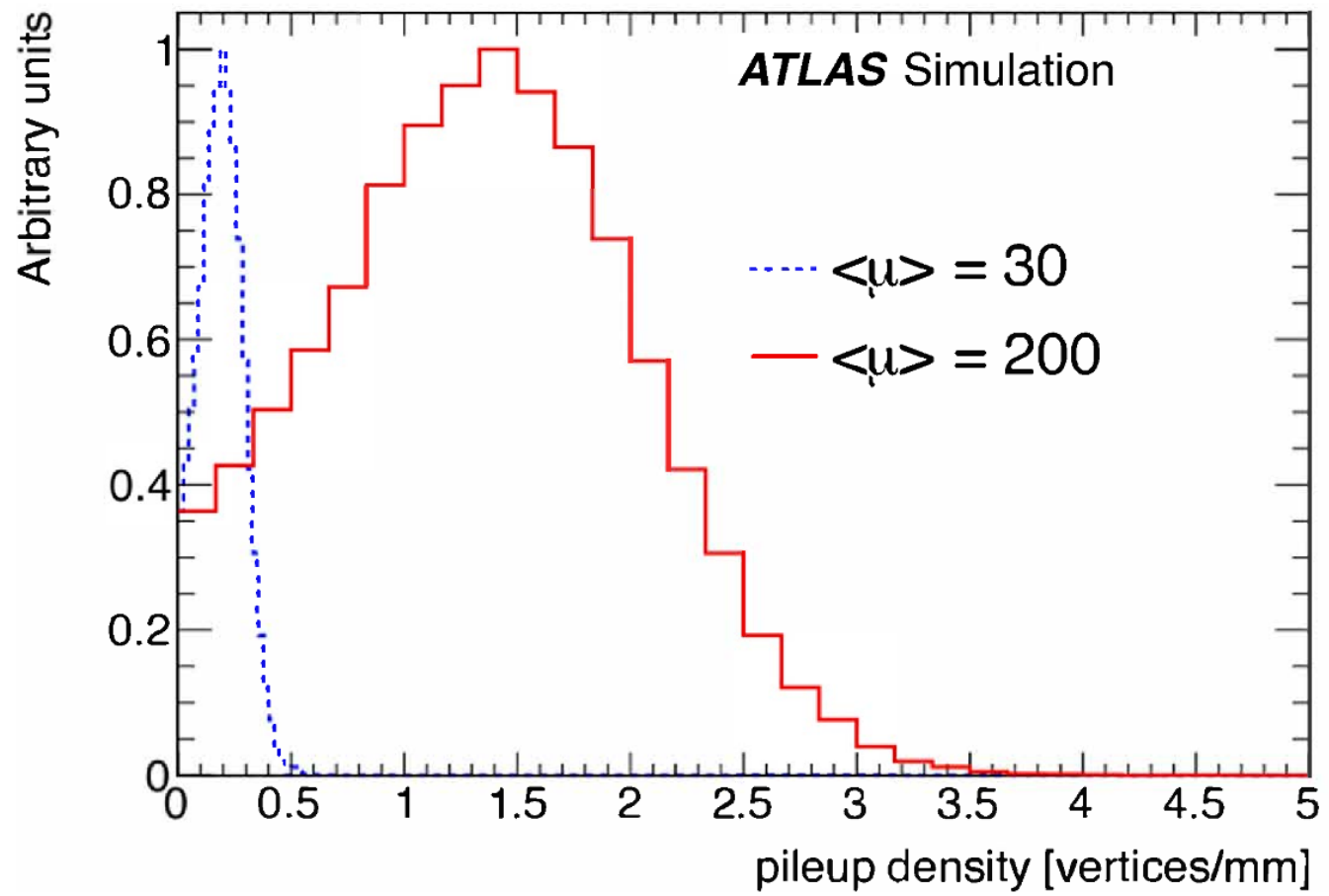


<10 ps after
correction



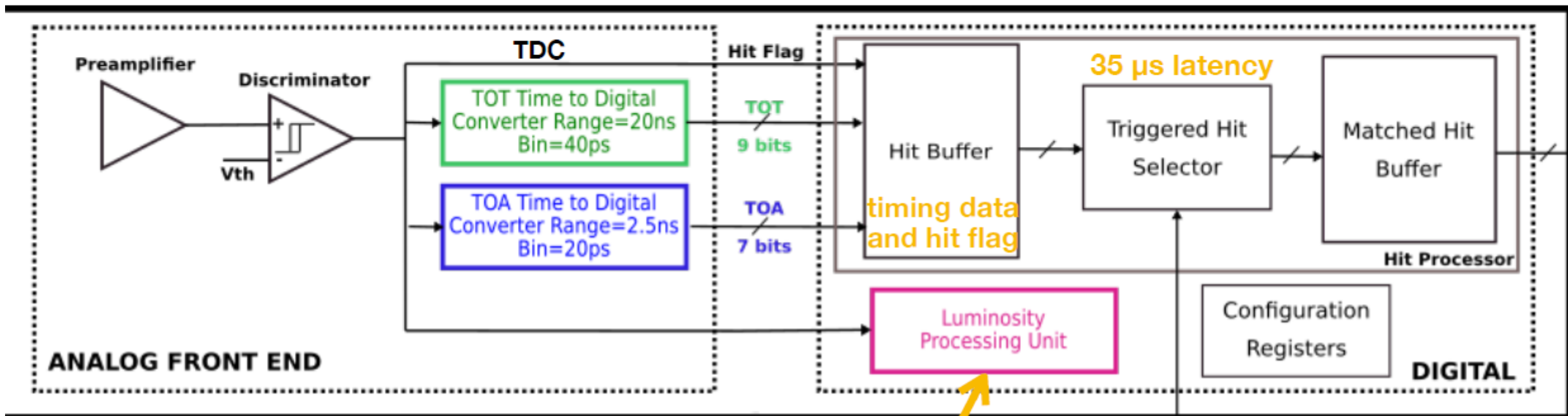
bin width,
20ps/√12

from clock
distribution, <10ps

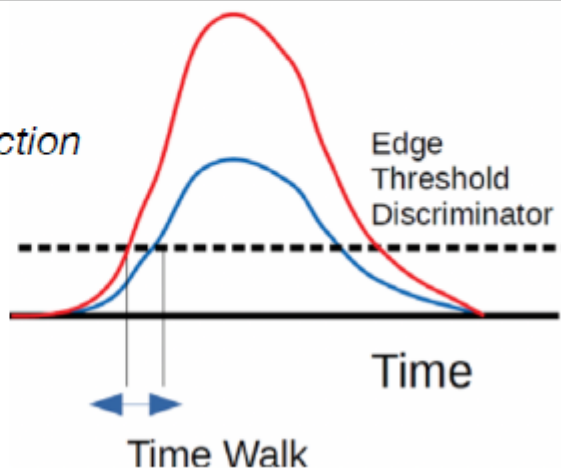


ALTIROC: ASIC architecture

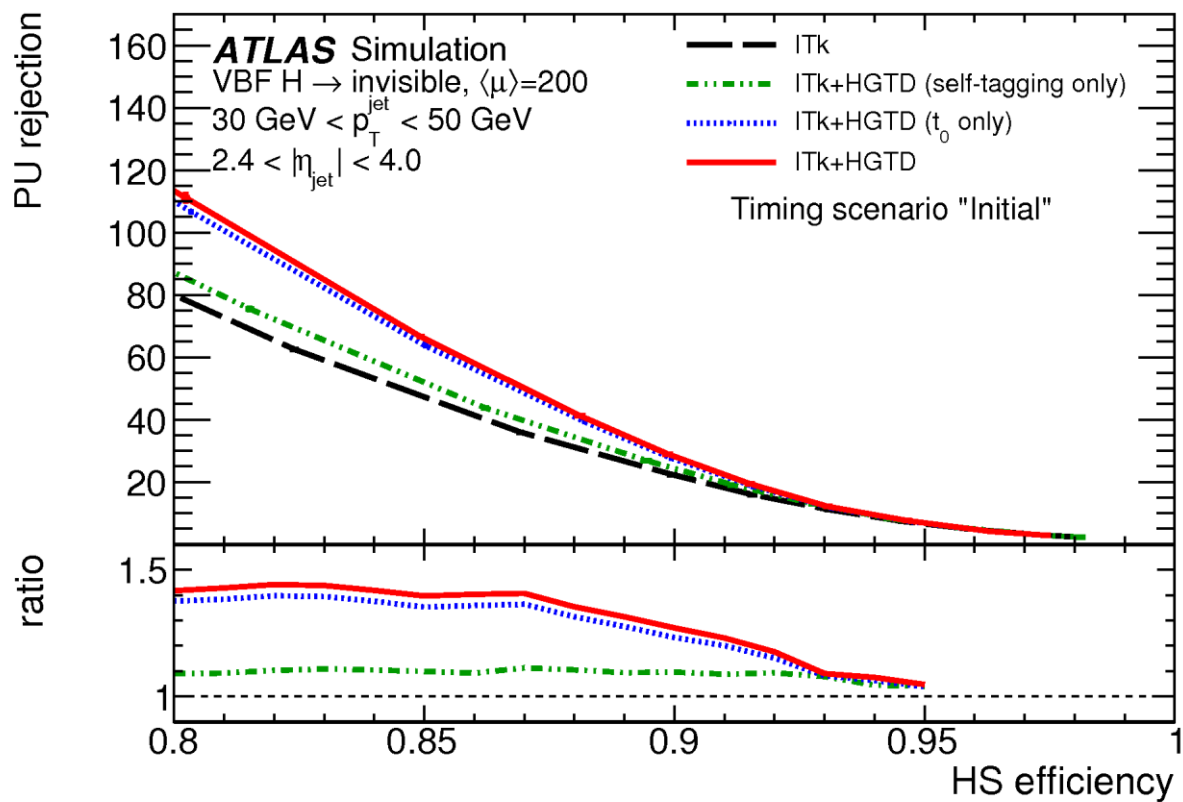
Repeat for 225 channels



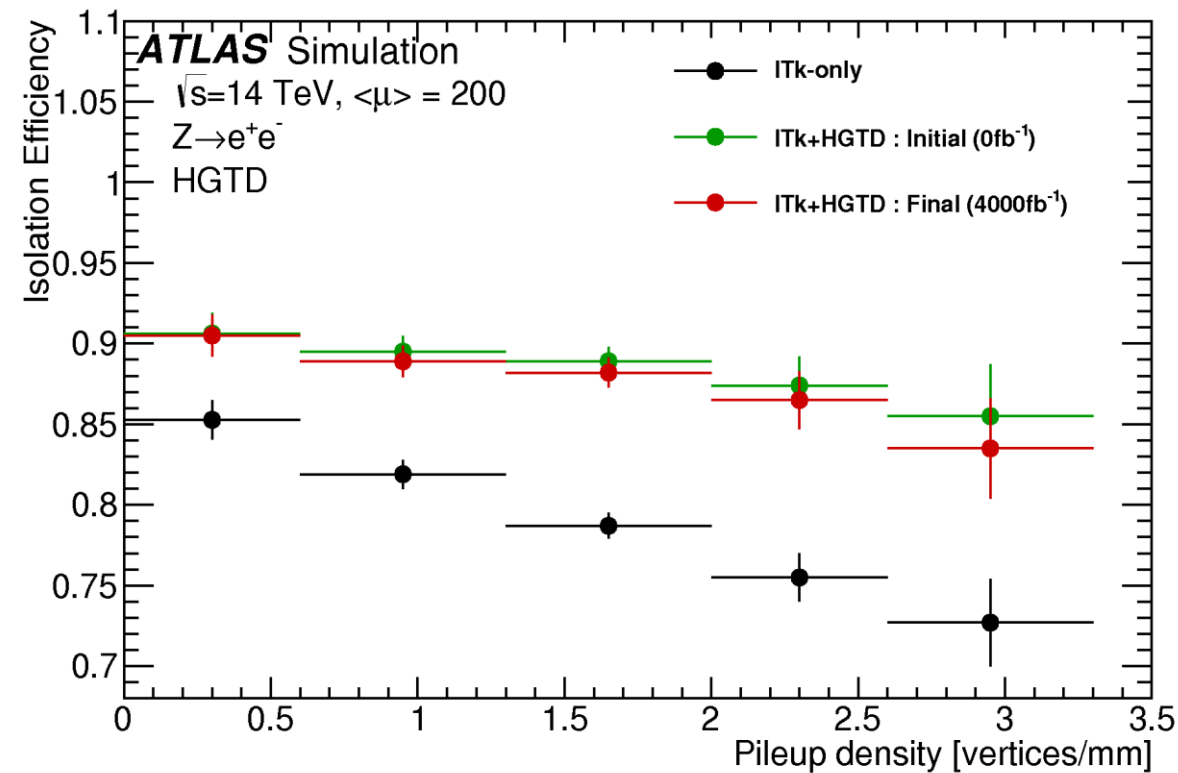
OA (Time of arrival) time walk correction using TOT (Time Over Threshold)



Luminosity data: sum of hits per bunch crossing



Suppression of pile-up jets



Efficiency of track isolation requirement for forward e^-

